

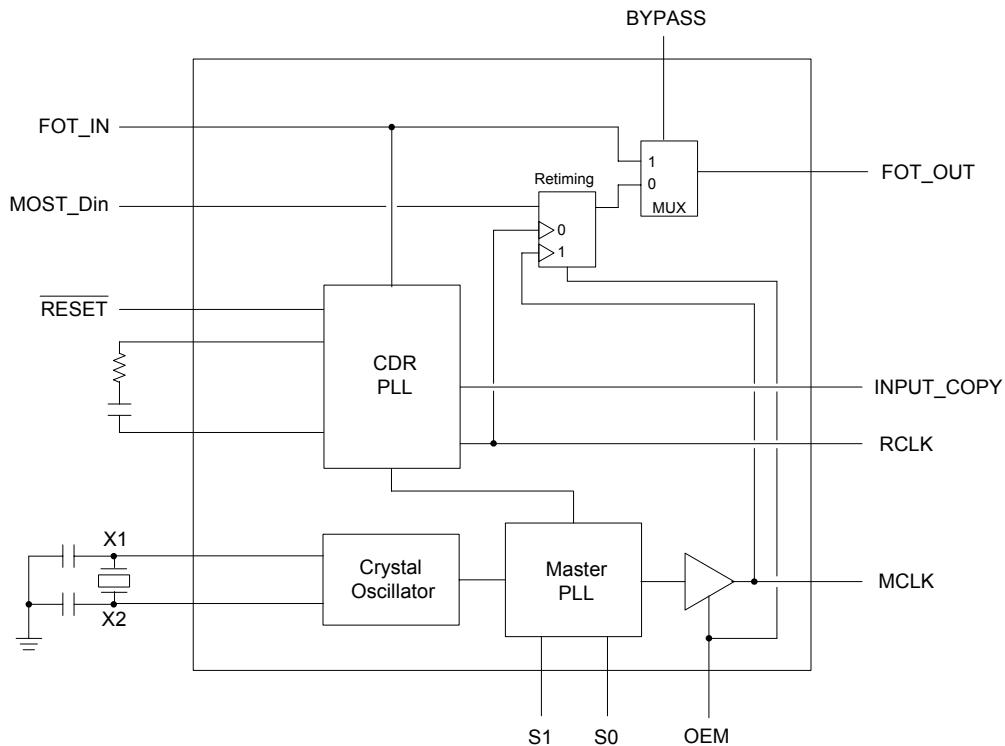
## Description

The IDT5V80001 is a high performance clock interface for use in MOST® (Media Oriented Systems Transport) enabled systems. It can be used in two modes: generating a master clock for the ring, or performing clock/data recovery in a slave node.

## Features

- Packaged in 20-pin TSSOP
- -40 to +85°C temperature range (industrial)
- Compliant to AEC Q100
- Operating voltage of 3.3 V
- 5 volt tolerant input for FOT
- Low jitter generation
- Power-down tri-state mode
- Advanced, low-power CMOS process

## Block Diagram



## Pin Assignment

|         |    |    |            |
|---------|----|----|------------|
| X2      | 1  | 20 | NC         |
| X1      | 2  | 19 | MOST_Din   |
| RESET   | 3  | 18 | INPUT_COPY |
| VDD     | 4  | 17 | VDD        |
| FOT_OUT | 5  | 16 | RCLK       |
| GND     | 6  | 15 | GND        |
| S1      | 7  | 14 | MCLK       |
| FOT_IN  | 8  | 13 | OEM        |
| S0      | 9  | 12 | BYPASS     |
| LF      | 10 | 11 | LFR        |

20-pin TSSOP

## Frequency Selection Tables

| S1 | S0 | Operating Frequency (RCLK) | Mode    | Sampling Frequency |
|----|----|----------------------------|---------|--------------------|
| 0  | 0  | 45.1584 MHz                | MOST 25 | 44.1 kHz           |
| 0  | 1  | 49.152 MHz                 | MOST 25 | 48 kHz             |
| 1  | 0  | 90.3168 MHz                | MOST 50 | 44.1 kHz           |
| 1  | 1  | 98.304 MHz                 | MOST 50 | 48 kHz             |

| OEM | MCLK Output | Source for Retiming Block |
|-----|-------------|---------------------------|
| 0   | LOW         | RCLK (slave node)         |
| 1   | Running     | MCLK (master node)        |

| OEM | Node   | Bypass | FOT_OUT                  |
|-----|--------|--------|--------------------------|
| 0   | Slave  | 0      | Retimed (RCLK) MOST_Din* |
|     |        | 1      | FOT_IN                   |
| 1   | Master | 0      | Retimed (MCLK) MOST_Din  |
|     |        | 1      | FOT_IN                   |

\* FOT\_IN must be present in order to generate RCLK and Retimed (RCLK) MOST\_Din.

## Pin Descriptions

| Pin | Name    | Type   | Pin Description   |
|-----|---------|--------|---|
| 1   | X2      | Input  | Connect to 21.504 MHz crystal.  |
| 2   | X1      | Input  | Connect to 21.504 MHz crystal.  |
| 3   | RESET   | Input  | Low to reset CDR PLL. Internal pull-up resistor.  |
| 4   | VDD     | Power  | Connect to 3.3 V supply.  |
| 5   | FOT_OUT | Output | Output for fiber optic MOST transceiver. 3.3 V LVTTL levels.                            |
| 6   | GND     | Power  | Connect to ground.  |
| 7   | S1      | Input  | Frequency select input pin. See table above. No internal pull-up or pull-down resistor. |
| 8   | FOT_IN  | Input  | Input to device from fiber optic MOST transceiver. 3.3 V LVTTL levels, 5 V tolerant.    |
| 9   | S0      | Input  | Frequency select input pin. See table above. No internal pull-up or pull-down resistor. |

| Pin | Name       | Type   | Pin Description  |
|-----|------------|--------|--|
| 10  | LF         | Input  | Loop filter connection for CDR PLL.  |
| 11  | LFR        | Input  | Loop filter return. Connected to ground internally.  |
| 12  | BYPASS     | Input  | MUX control to bypass CDR PLL. Active high. No internal pull-up or pull-down resistor.               |
| 13  | OEM        | Input  | High to enable MCLK. See table above. No internal pull-up or pull-down resistor.                     |
| 14  | MCLK       | Output | Master clock output. Clean clock derived from crystal. See table above. Weak pull-down when OEM = 0. |
| 15  | GND        | Power  | Connect to ground.   |
| 16  | RCLK       | Output | Recovered clock out. See table above.  |
| 17  | VDD        | Power  | Connect to 3.3 V supply.   |
| 18  | INPUT_COPY | Output | Retimed copy of FOT_IN input.  |
| 19  | MOST_Din   | Input  | MOST data input.   |
| 20  | NC         | —      | No Connect. Do not connect this pin to anything.   |

## Operation

The IDT5V80001 performs clock generation and recovery for either a master or slave node in a MOST ring. It provides a interface between a controller (typically implemented in an ASIC or FPGA) and the fiber optic transceiver (FOT).

When used in a Master node (OEM = High), the Master PLL synthesizes a frequency of twice the MOST data rate as the MCLK output, and also reclocks the data from the controller that is input on the FOT\_IN pin to the INPUT\_COPY output. The output data on FOT\_OUT is the MOST\_Din data retimed to MCLK if BYPASS is driven low, or the FOT\_IN data if BYPASS is driven high. Simultaneously, the device recovers the clock from data on the FOT\_IN pin and outputs a 2x clock on RCLK.

In a slave node, OEM is set low and the MCLK output is disabled. Data from the controller (FOT\_IN) is retimed using the recovered clock and output on the INPUT\_COPY. If BYPASS is driven high, the controller data (FOT\_IN) is also transmitted on the FOT\_OUT output but is not retimed to RCLK. If BYPASS is driven low, the MOST\_Din data is retimed and transmitted on the FOT\_OUT output.

To recover the clock from the data stream, the two PLLs work together. The lock sequence from power on is:

1. Crystal oscillator starts and stabilizes.
2. Master (frequency synthesis) PLL starts and locks to the crystal.
3. CDR PLL starts and locks to the master PLL to obtain a frequency operation point.
4. Activity is detected on FOT\_IN.
5. CDR PLL phase-locks to incoming data.

Extreme conditions, such as electrical transients, phase steps or brief dropouts on the FOT\_IN pin may cause the CDR PLL to unlock. If this occurs and the controller begins to experience data errors, it should set RESET low for at least 50 ns to restart the data lock sequence from step 3.

## External Components

The IDT5V80001 requires a minimum number of external components for proper operation.

### Decoupling Capacitor

A decoupling capacitor of  $0.01\mu\text{F}$  must be connected between each VDD pins and the ground plane, as close to these pins as possible. For optimum device performance, the decoupling capacitor should be mounted on the component side of the PCB.

### Crystal

The IDT5V80001 requires a 21.504 MHz parallel resonant crystal. Recommended devices are:

| Manufacturer | Package          | Part #            |
|--------------|------------------|-------------------|
| Abracon      | 5x7 mm ceramic   | AAH-363-21.504MHz |
| NDK          | 3.2x5 mm ceramic | EXS00A-CG00294    |

### Crystal Load Capacitors

The device crystal connections should include pads for capacitors from X1 to ground and from X2 to ground. These capacitors are used to adjust the stray capacitance of the board to match the nominally required crystal load capacitance.

The value (in pF) of these crystal caps should equal  $(C_L - 12\text{ pF})/2$ . In this equation,  $C_L$  = crystal load capacitance in pF. For the specified 16 pF load capacitance, each crystal capacitor would be 8 pF  $[(16-12) \times 2 = 8]$ .

### External Loop Filter

An external loop filter is required for operation of the CDR PLL. Recommended components are:

$R_S = 1210\ \Omega$ , 1% tolerance

$C_S = 10\text{ nF}$ , use capacitor with a non-piezoelectric dielectric. Recommended type is Panasonic ECH-U01103GX5 or equivalent.

### Series Termination Resistor

Termination should be used on the FOT\_OUT, MCLK, RCLK, and INPUT\_COPY output (pins 5, 14, 16, and 18 respectively). To series terminate a  $50\ \Omega$  trace (a commonly used trace impedance) place a  $33\ \Omega$  resistor in series with the clock line, as close to the clock output pin as possible.

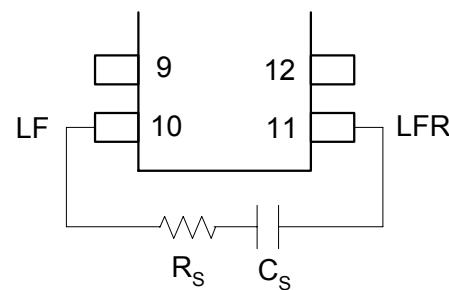
The nominal impedance of the clock output is  $20\ \Omega$

### PCB Layout Recommendations

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

- 1) The  $0.01\mu\text{F}$  decoupling capacitors should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between decoupling capacitor and VDD pin. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via.
- 2) The external crystal should be mounted just next to the device with short traces.
- 3) The external loop filter components should be mounted close to the IDT5V80001 and away from digital signals, switching power supply components, and other sources of noise.
- 4) To minimize EMI,  $33\ \Omega$  series termination resistors should be placed close to the clock outputs.
- 5) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers. Other signal traces should be routed away from the IDT5V80001. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

### External Loop Filter



## Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the IDT5V80001. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| Item                  | Rating              |
|-----------------------|---------------------|
| Supply Voltage, VDD   | 7 V                 |
| Inputs and Outputs    | -0.5 V to VDD+0.5 V |
| Input (FOT_IN only)   | 7 V                 |
| Storage Temperature   | -65 to +150°C       |
| Junction Temperature  | 125°C               |
| Soldering Temperature | 260°C               |

## Recommended Operation Conditions

| Parameter   | Min. | Typ.  | Max. | Units |
|---|------|-------|------|-------|
| Ambient Operating Temperature                       | -40  |       | +85  | °C    |
| Power Supply Voltage (measured with respect to GND) | +3.0 | +3.3V | +3.6 | V     |
| Power Supply Ramp Time                              |      |       | 4    | ms    |

## DC Electrical Characteristics

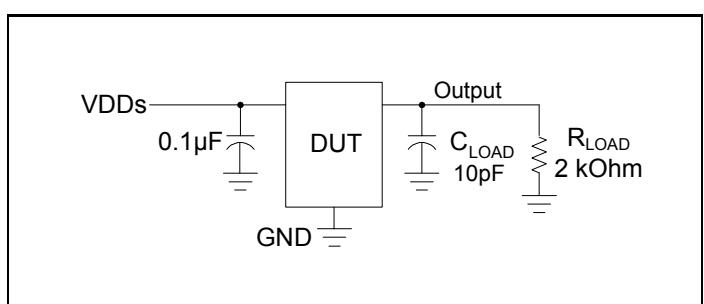
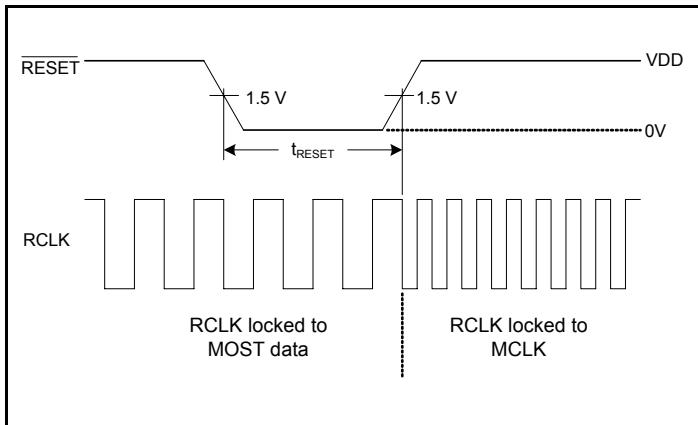
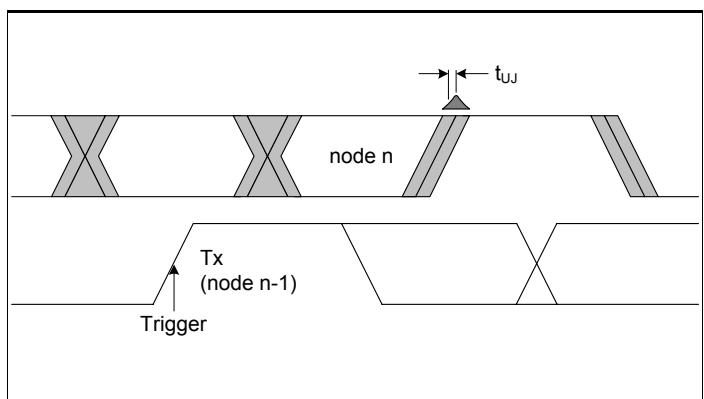
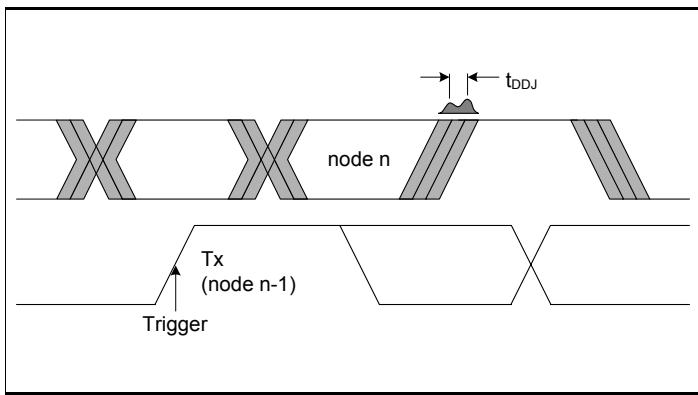
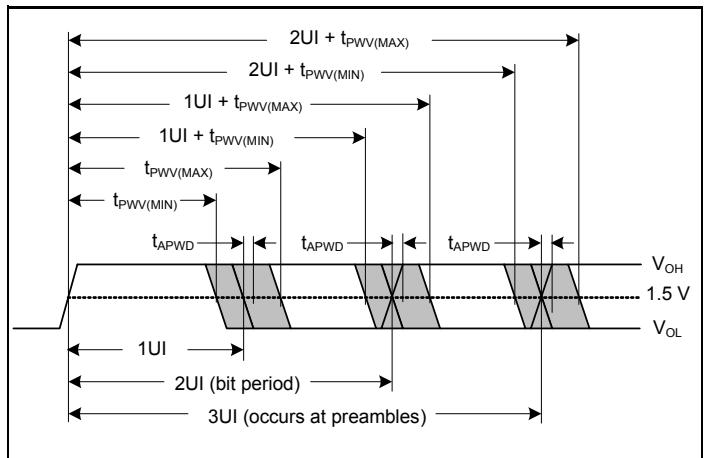
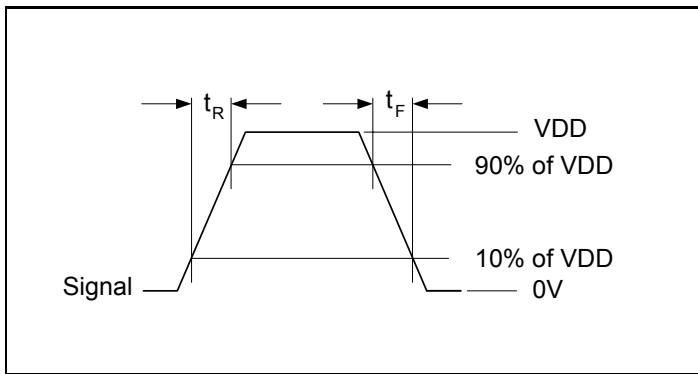
Unless stated otherwise,  $VDD = 3.3\text{ V} \pm 10\%$ , Ambient Temperature -40 to +85°C

| Parameter                             | Symbol    | Conditions   | Min.      | Typ. | Max.      | Units |
|---------------------------------------|-----------|--|-----------|------|-----------|-------|
| Operating Supply Current              | IDD       | No load, $F_{RCLK} = 49.152\text{ MHz}$                      |           | 35   |           | mA    |
| High Level Input Voltage              | $V_{IH}$  | FOT_IN, MOST_Din   | 2         |      | 5.5       | V     |
|                                       |           | RESET, BYPASS, OEM, S0, S1                                   | 2.0       |      | $VDD+0.3$ |       |
| Low Level Input Voltage               | $V_{IL}$  | FOT_IN, MOST_Din   | -0.3      |      | 0.8       | V     |
|                                       |           | RESET, BYPASS, OEM, S0, S1                                   | -0.3      |      | 0.8       |       |
| High Level Output Voltage             | $V_{OH}$  | FOT_OUT only, $I_{OH} = -2\text{ mA}$                        | 2.4       |      |           | V     |
|                                       |           | MCLK, RCLK, INPUT_COPY<br>$I_{OH} = -100\text{ }\mu\text{A}$ | $VDD-0.2$ |      |           |       |
| Low Level Output Voltage              | $V_{OL}$  | FOT_OUT only, $I_{OH} = 2\text{ mA}$                         |           |      | 0.4       | V     |
|                                       |           | MCLK, RCLK, INPUT_COPY<br>$I_{OH} = 100\text{ }\mu\text{A}$  |           |      | 0.2       |       |
| Short Circuit Current                 | $I_{OS}$  | FOT_OUT  |           | 35   |           | mA    |
| Input Capacitance                     | $C_{IN}$  | FOT_IN, MOST_Din, RESET, BYPASS, OEM, S0, S1                 |           | 5    | 10        | pF    |
| Nominal Output Impedance              | $Z_{OUT}$ | FOT_OUT, MCLK, RCLK, INPUT_COPY                              |           | 20   |           | Ω     |
| On-Chip Pull-up or Pull-down Resistor | $R_P$     | RESET  |           | 500  |           | kΩ    |

## Timing Requirements

| Parameter  | Symbol      | Conditions              | Min. | Typ.   | Max. | Units |
|--|-------------|-------------------------|------|--------|------|-------|
| Crystal Frequency  | $F_{IN}$    |                         |      | 21.504 |      | MHz   |
| Input Rise Time  | $t_R$       | S1=0, S0=0 (See Fig. 1) |      |        | 10.0 | ns    |
|  |             | S1=0, S0=1 (See Fig. 1) |      |        | 9.2  |       |
|  |             | S1=1, S0=0 (See Fig. 1) |      |        | 5.0  |       |
|  |             | S1=1, S0=1 (See Fig. 1) |      |        | 4.6  |       |
| Input Fall Time  | $t_F$       | S1=0, S0=0 (See Fig. 1) |      |        | 10.0 | ns    |
|  |             | S1=0, S0=1 (See Fig. 1) |      |        | 9.2  |       |
|  |             | S1=1, S0=0 (See Fig. 1) |      |        | 5.0  |       |
|  |             | S1=1, S0=1 (See Fig. 1) |      |        | 4.6  |       |
| Input Pulse Width Variation (FOT_IN and MOST_Din)          | $t_{PWV}$   | S1=0, S0=0 (See Fig. 2) | 16.4 |        | 31.1 | ns    |
|  |             | S1=0, S0=1 (See Fig. 2) | 15.1 |        | 28.5 |       |
|  |             | S1=1, S0=0 (See Fig. 2) | 8.2  |        | 15.6 |       |
|  |             | S1=1, S0=1 (See Fig. 2) | 7.5  |        | 14.3 |       |
| Average Input Pulse Width Distortion (FOT_IN and MOST_Din) | $t_{APWD}$  | S1=0, S0=0 (See Fig. 2) | -3.4 |        | +7.0 | ns    |
|  |             | S1=0, S0=1 (See Fig. 2) | -3.1 |        | +6.5 |       |
|  |             | S1=1, S0=0 (See Fig. 2) | -1.7 |        | +3.5 |       |
|  |             | S1=1, S0=1 (See Fig. 2) | -1.6 |        | +3.3 |       |
| One-Sigma Data Dependent Jitter (FOT_IN)                   | $t_{DDJ}$   | S1=0, S0=0 (See Fig. 3) | 0    |        | 3.4  | ns    |
|  |             | S1=0, S0=1 (See Fig. 3) | 0    |        | 3.1  |       |
|  |             | S1=1, S0=0 (See Fig. 3) | 0    |        | 1.7  |       |
|  |             | S1=1, S0=1 (See Fig. 3) | 0    |        | 1.6  |       |
| One-Sigma Uncorrelated Jitter                              | $t_{UJ}$    | S1=0, S0=0 (See Fig. 4) | 0    |        | 1000 | ps    |
|  |             | S1=0, S0=1 (See Fig. 4) | 0    |        | 920  |       |
|  |             | S1=1, S0=0 (See Fig. 4) | 0    |        | 500  |       |
|  |             | S1=1, S0=1 (See Fig. 4) | 0    |        | 460  |       |
| CDR Reset Time   | $t_{RESET}$ | (see Fig. 5)            | 50   |        |      | ns    |

## Timing Diagrams



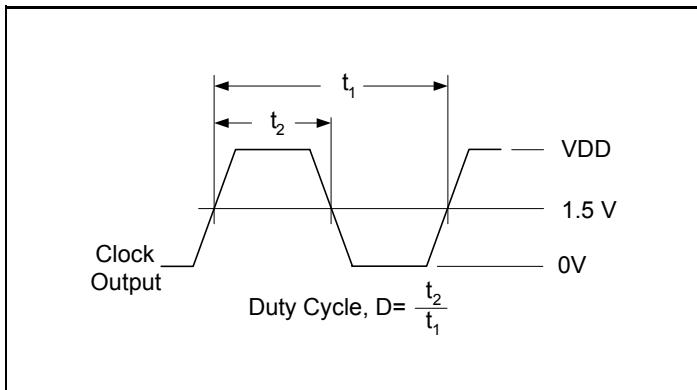


Figure 7: Duty Cycle Definitions

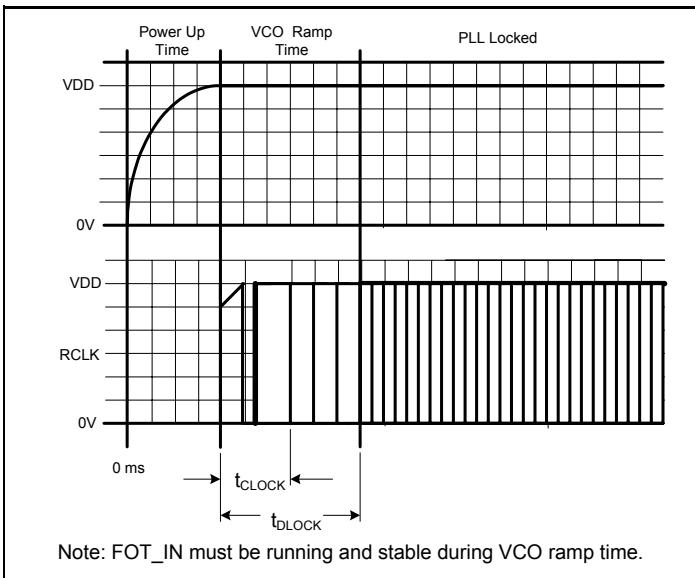


Figure 8: Power Up and PLL Lock Timing

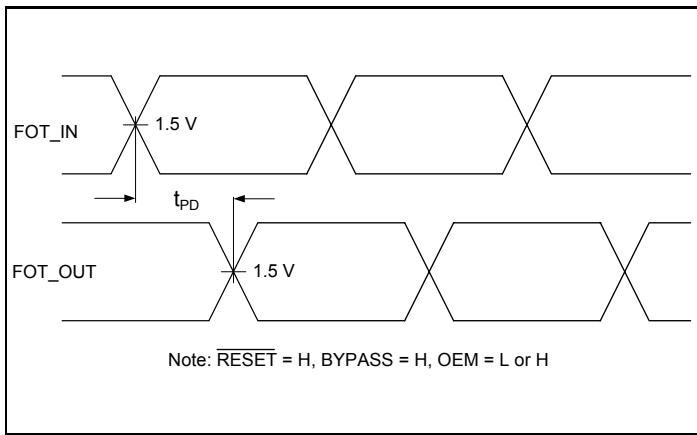


Figure 9: Propagation Delay

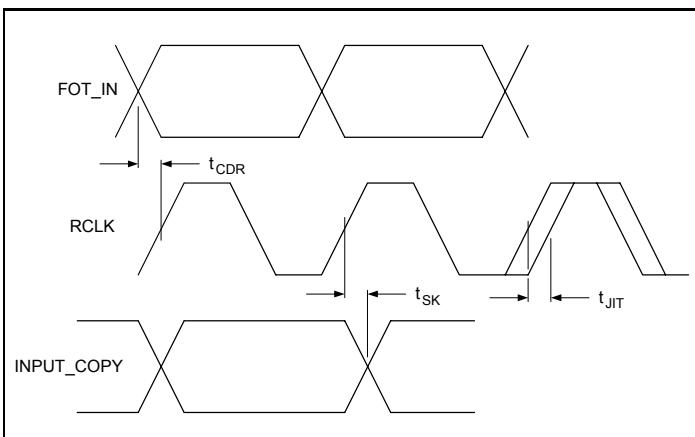


Figure 10: Clock Timing

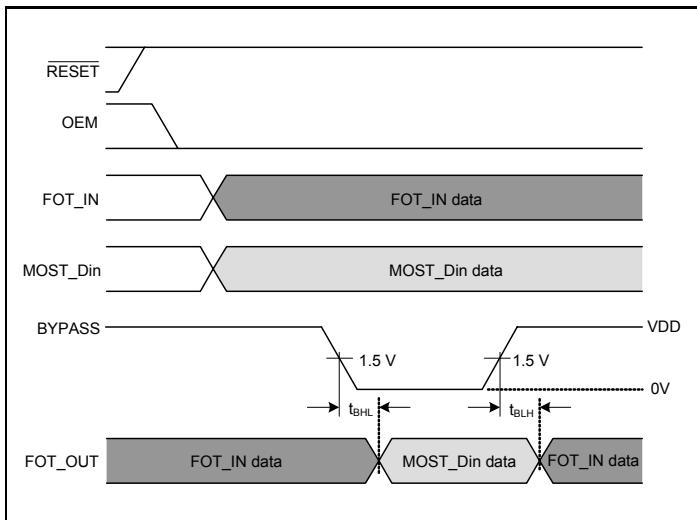


Figure 11: BYPASS Timing Definition

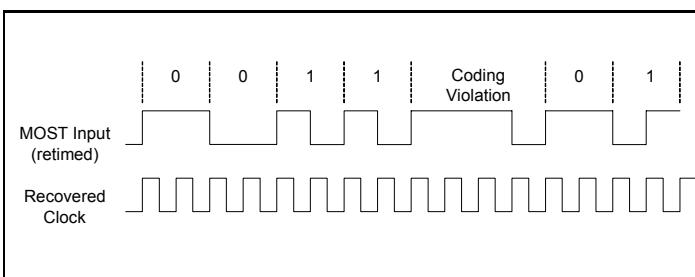


Figure 12: MOST Data-Clock Example

## AC Electrical Characteristics

Unless stated otherwise,  $VDD = 3.3 \text{ V} \pm 10\%$ , Ambient Temperature -40 to +85° C

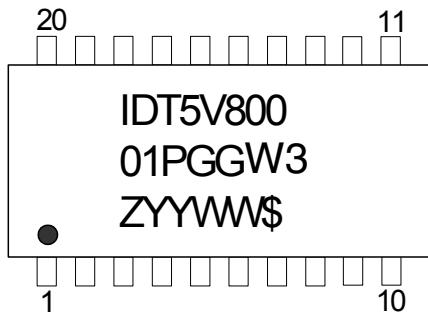
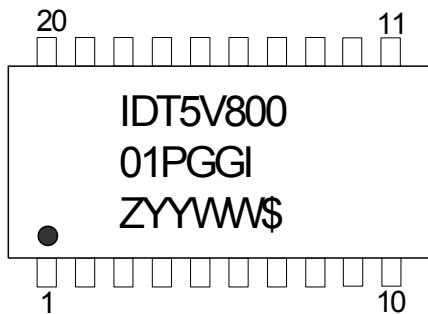
| Parameter                                       | Symbol      | Conditions   | Min. | Typ.   | Max. | Units |
|---|-------------|--|------|--------|------|-------|
| Crystal Frequency                               | $F_{IN}$    |  |      | 21.504 |      | MHz   |
| Output Frequency Error                          |             | Due to frequency synthesis   |      | 0      |      | ppm   |
| Output Clock Duty Cycle                         | D           | Figures 6 and 7  | 45   | 50     | 55   | %     |
| Output Rise Time                                | $t_R$       | S1=0, S0=0 (See Fig. 1)  |      | 5.0    |      | ns    |
|   |             | S1=0, S0=1 (See Fig. 1)  |      | 4.6    |      |       |
|   |             | S1=1, S0=0 (See Fig. 1)  |      | 2.5    |      |       |
|   |             | S1=1, S0=1 (See Fig. 1)  |      | 2.3    |      |       |
| Output Fall Time                                | $t_F$       | S1=0, S0=0 (See Fig. 1)  |      | 5.0    |      | ns    |
|   |             | S1=0, S0=1 (See Fig. 1)  |      | 4.6    |      |       |
|   |             | S1=1, S0=0 (See Fig. 1)  |      | 2.5    |      |       |
|   |             | S1=1, S0=1 (See Fig. 1)  |      | 2.3    |      |       |
| Output Pulse Width Variation (FOT_OUT)          | $t_{PWV}$   | S1=0, S0=0 (See Fig. 2)  | 21.2 |        | 23.1 | ns    |
|   |             | S1=0, S0=1 (See Fig. 2)  | 19.5 |        | 21.2 |       |
|   |             | S1=1, S0=0 (See Fig. 2)  | 10.6 |        | 11.5 |       |
|   |             | S1=1, S0=1 (See Fig. 2)  | 9.8  |        | 10.6 |       |
| Average Output Pulse Width Distortion (FOT_OUT) | $t_{APWD}$  | S1=0, S0=0 (See Fig. 2)  | -500 |        | +500 | ps    |
|   |             | S1=0, S0=1 (See Fig. 2)  | -460 |        | +460 |       |
|   |             | S1=1, S0=0 (See Fig. 2)  | -250 |        | +250 |       |
|   |             | S1=1, S0=1 (See Fig. 2)  | -230 |        | +230 |       |
| One-Sigma Data dependent Jitter (RCLK)          | $t_{DDJ}$   | S1=0, S0=0 (See Fig. 3)  | 0    |        | 220  | ps    |
|   |             | S1=0, S0=1 (See Fig. 3)  | 0    |        | 200  |       |
|   |             | S1=1, S0=0 (See Fig. 3)  | 0    |        | 110  |       |
|   |             | S1=1, S0=1 (See Fig. 3)  | 0    |        | 100  |       |
| One-Sigma Uncorrelated Jitter (RCLK)            | $t_{UJ}$    | S1=0, S0=0 (See Fig. 4)  | 0    |        | 95   | ps    |
|   |             | S1=0, S0=1 (See Fig. 4)  | 0    |        | 90   |       |
|   |             | S1=1, S0=0 (See Fig. 4)  | 0    |        | 45   |       |
|   |             | S1=1, S0=1 (See Fig. 4)  | 0    |        | 45   |       |
| Power-up Time                                   | $t_{CLOCK}$ | PLL lock-time from 90% VDD to RCLK = MCLK, (see Fig. 8)                          |      |        | 200  | μs    |
|   | $t_{DLOCK}$ | PLL lock-time from beginning of FOT_IN input to stable RCLK output, (see Fig. 8) |      |        | 400  | μs    |
| Propagation Delay (FOT_IN to FOT_OUT)           | $t_{PD}$    | (see Fig. 9)   | 3    | 4      | 5    | ns    |
| Propagation Delay (FOT_IN to RCLK)              | $t_{CDR}$   | (see Fig. 10)  | TBD  | TBD    | TBD  | ns    |
| Skew, recovered clock to retimed input          | $t_{SK}$    | (see Fig. 10)  | -250 | 0      | +250 | ps    |
| One-Sigma Clock Period Jitter                   |             | MCLK   | 0    |        | 50   | ps    |

| Parameter                                       | Symbol    | Conditions    | Min. | Typ. | Max. | Units |
|---|-----------|---------------|------|------|------|-------|
| RCLK Peak-to-peak Jitter with respect to FOT_IN | $t_{JIT}$ |               | -500 | 0    | +500 | ps    |
| BYPASS High-to-Low to FOT_OUT                   | $t_{BHL}$ | (see Fig. 11) | TBD  |      | TBD  | ns    |
| BYPASS Low-to-High to FOT_OUT                   | $t_{BLH}$ | (see Fig. 11) | TBD  |      | TBD  | ns    |

## Thermal Characteristics

| Parameter                              | Symbol        | Conditions     | Min. | Typ. | Max. | Units |
|--|---------------|----------------|------|------|------|-------|
| Thermal Resistance Junction to Ambient | $\theta_{JA}$ | Still air      |      | 93   |      | °C/W  |
|  | $\theta_{JA}$ | 1 m/s air flow |      | 78   |      | °C/W  |
|  | $\theta_{JA}$ | 3 m/s air flow |      | 65   |      | °C/W  |
| Thermal Resistance Junction to Case    | $\theta_{JC}$ |                |      | 20   |      | °C/W  |

## Marking Diagrams

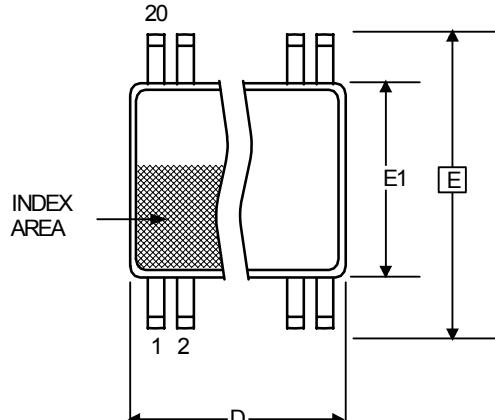


### Notes:

1. "Z" is the device step (1 to 2 characters).
2. YYWW is the last two digits of the year and week that the part was assembled.
3. "\$" is the assembly mark code.
4. "G" after the two-letter package code designates RoHS compliant package.
5. "I" at the end of part number indicates industrial temperature range.
6. 'W3' denotes automotive grade.
7. Bottom marking: country of origin if not USA.

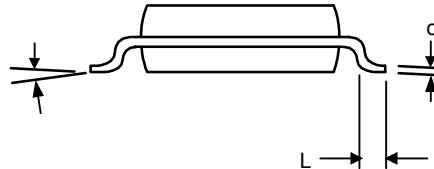
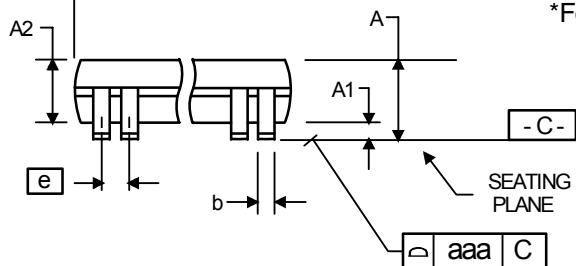
## Package Outline and Package Dimensions (20-pin TSSOP, 4.4mm Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95



| Symbol | Millimeters |      | Inches*      |       |
|--------|-------------|------|--------------|-------|
|        | Min         | Max  | Min          | Max   |
| A      | --          | 1.20 | --           | 0.047 |
| A1     | 0.05        | 0.15 | 0.002        | 0.006 |
| A2     | 0.80        | 1.05 | 0.032        | 0.041 |
| b      | 0.19        | 0.30 | 0.007        | 0.012 |
| C      | 0.09        | 0.20 | 0.0035       | 0.008 |
| D      | 6.40        | 6.60 | 0.252        | 0.260 |
| E      | 6.40 BASIC  |      | 0.252 BASIC  |       |
| E1     | 4.30        | 4.50 | 0.169        | 0.177 |
| e      | 0.65 Basic  |      | 0.0256 Basic |       |
| L      | 0.45        | 0.75 | 0.018        | 0.030 |
| α      | 0°          | 8°   | 0°           | 8°    |
| aaa    | --          | 0.10 | --           | 0.004 |

\*For reference only. Controlling dimensions in mm.



## Ordering Information

| Part / Order Number | Marking    | Shipping Packaging | Package      | Temperature   |
|---------------------|------------|--------------------|--------------|---------------|
| 5V80001PGGI         | see page 8 | Tubes              | 20-pin TSSOP | -40 to +85° C |
| 5V80001PGGI8        |            | Tape and Reel      | 20-pin TSSOP | -40 to +85° C |
| 5V80001PGGW3        | see page 8 | Tubes              | 20-pin TSSOP | -40 to +85° C |
| 5V80001PGGW38       |            | Tape and Reel      | 20-pin TSSOP | -40 to +85° C |

Parts that are ordered with a "G" after the two-letter package code are the Pb-Free configuration and are RoHS compliant.  
'W3' denotes automotive grade.

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## Revision History

| Rev. | Originator | Date     | Description of Change   |
|------|------------|----------|---|
| A    | J. Gazda   | 08/29/06 | Preliminary datasheet.  |
| B    | J. Gazda   | 09/19/06 | Changed block diagram and pinout;   |
| C    | J. Gazda   | 09/25/06 | Changed from 16-pin TSSOP to 20-pin TSSOP; added timing diagrams; changed pinout and block diagrams.  |
| D    | J. Gazda   | 09/27/06 | New block diagram; changed pinout; added Propagation Delay, Skew, and Clock Jitter specs; changed High/Low Input/Output level specs.  |
| E    | J. Gazda   | 11/02/06 | Changed temperature rating from -40/+85 to -40/+105 °C; added "Mode" and "Sampling Frequency" to Frequency Selection Table.   |
| F    | J. Gazda   | 12/14/06 | Added "Operation" section; added "External Loop Filter" diagram; added RESET# pin; various modifications to "External Components" text.   |
| G    | J. Gazda   | 02/15/07 | Added Feature bullet of "5 V tolerant input for FOT"; add crystal caps and ground to block diagram; added "Weak pull-down when OEM=0" statement to MCLK pin description.  |
| H    | J. Gazda   | 03/22/07 | Added NDK crystal part number; changed "MCLK" to "RCLK" in the conditions for "Data to clock jitter" spec.  |
| J    | J. Gazda   | 05/31/07 | Removed C <sub>P</sub> reference on External Loop Filter descriptions; removed one capacitor from "CDR PLL" in Block Diagram.   |
| K    | J. Gazda   | 06/22/07 | Reversed '1' and '0' on the MUX in the block diagram; removed the bar from "BYPASS"; added the text "No pull-up" to pin descriptions 7, 9, 12, and 13; removed "Data to clock jitter" spec from AC char table.  |
| L    | J. Gazda   | 10/09/07 | Removed "Lock" pin.   |
| M    | T. Nana    | 12/17/07 | Updates to timing diagrams; added "Timing Requirements" table; updates to pin descriptions; multiple updates to AC/DC char tables; added Figure 7.  |
| N    | T. Nana    | 12/26/07 | Updates to Block Diagram and Timing diagrams; added new "Operation" information; added another OEM table for BYPASS and FOT_OUT; updates to AC/DC char tables and "Timing Requirements" table; added "Reset Timing Definition" (Fig. 8) and "BYPASS Timing Definition" (Fig. 9) diagrams. |
| P    | T. Nana    | 01/08/08 | Updates to DC Electrical Char table; One-Sigma Jitter specs added to "Timing Requirements" table; updates to Timing Diagrams; added jitter and propagation delay timing diagrams; added One-Sigma Jitter specs to AC Electrical Char table;   |
| Q    | T. Nana    | 02/06/08 | Removed OEM and MUX from Block Diagram; updates to "Operation" text; updated "Propagation Delay" diagram; added additional "Propagation Delay" spec to AC char table.   |
| R    |            | 11/14/08 | Moved from Preliminary to Released.   |
| S    | D.L.       | 08/31/09 | Added automotive grade ordering info and marking diagram  |



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